

IN THE SPECIFICATION

On page 1, after the Title, insert:

--Cross-Reference To Related Applications

This application is a continuation of U.S. Application Serial No. 10/342,955 filed January 15, 2003, which is a divisional of U.S. Application Serial No. 09/210,517 filed December 11, 1998, now issued as U.S. Patent No. 6,523,736 on February 25, 2003.--

IN THE CLAIMS

Please cancel claims 1-34 and 36-53 without prejudice.

Please amend claim 35 as set forth below:

35. (Once Amended) A method of forming solder balls, the method comprising the acts of:

(a) ~~providing a stencil disposed on a substrate, the stencil having a plurality of holes therein;~~

(b) ~~—disposing solder within the a plurality of holes~~receptacles disposed within a surface of a conveyor belt; and

(eb) heating the solder disposed within the ~~holes of the stencil disposed on the substrate~~receptacles to form a solder ball within each ~~hole~~receptacle.

Please add claims 54-61 as set forth below:

54. The method as recited in claim 35, wherein disposing solder within the plurality of receptacles comprises disposing solder within the plurality of receptacles formed by a first portion of the conveyor belt having a plurality of holes disposed upon a second portion of the conveyor belt.